

## TRENCHSTOP™ IGBT3 Chip

### Features:

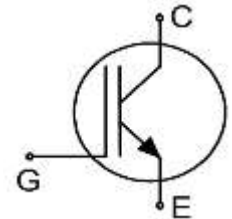
- 600V trench & field stop technology
- Low  $V_{CEsat}$
- Low turn-off losses
- Short tail current
- Positive temperature coefficient
- Easy paralleling

### Recommended for:

- Power modules
- Discrete components

### Applications:

- Drives
- White goods
- Resonant applications



Chip Type	$V_{CE}$	$I_{Cn}$	Die Size	Package
SIGC04T60E	600V	6A	1.98mm x 1.96mm	Sawn on foil

### Mechanical Parameters

Die size	1.98 x 1.96	mm <sup>2</sup>
Emitter pad size	See chip drawing	
Gate pad size	0.27 x 0.27	
Area total	3.88	
Silicon thickness	70	μm
Wafer size	200	mm
Maximum possible chips per wafer	7216	
Passivation frontside	Photoimide	
Pad metal	3200nm AlSiCu	
Backside metal	Ni Ag – system To achieve a reliable solder connection it is strongly recommended not to consume the Ni layer completely during production process	
Die bond	Electrically conductive epoxy glue and soft solder	
Wire bond	Al, ≤500μm	
Reject ink dot size	∅ 0.65mm; max. 1.2mm	
Storage environment (<6 months)	for original and sealed MBB bags	Ambient atmosphere air, temperature 17°C – 25°C
	for open MBB bags	Acc. IEC 62258-3; Section 9.4 Storage Environment.

## Maximum Ratings

In general, from reliability and lifetime point of view, the lower the operation junction temperature and/or the applied voltage, the greater the expected lifetime of any semiconductor device.

Parameter	Symbol	Value	Unit
Collector-emitter voltage, $T_{vj}=25^{\circ}\text{C}$	$V_{CE}$	600	V
DC collector current, limited by $T_{vj\text{ max}}^1$	$I_C$	-	A
Pulsed collector current, $t_p$ limited by $T_{vj\text{ max}}^2$	$I_{C,puls}$	18	A
Gate-emitter voltage	$V_{GE}$	$\pm 20$	V
Virtual junction temperature	$T_{vj}$	-40 ... +175	$^{\circ}\text{C}$
Short circuit data <sup>1/2/3</sup> $V_{GE}=15\text{V}$ , $V_{CC}=360\text{V}$ , $T_{vj}=150^{\circ}\text{C}$	$t_{sc}$	6	$\mu\text{s}$
Reverse bias safe operating area (RBSOA) <sup>2</sup>	$I_{C,max} = 12\text{A}$ , $V_{CE,max} = 600\text{V}$ , $T_{vj} \leq 150^{\circ}\text{C}$		

## Static Characteristics (tested on wafer), $T_{vj}=25^{\circ}\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0\text{V}$ , $I_C=2\text{mA}$	600	-	-	V
Collector-emitter saturation voltage	$V_{CEsat}$	$V_{GE}=15\text{V}$ , $I_C=6\text{A}$	1.1	1.5	1.9	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=90\mu\text{A}$ , $V_{GE}=V_{CE}$	5.0	5.8	6.5	
Zero gate voltage collector current	$I_{CES}$	$V_{CE}=600\text{V}$ , $V_{GE}=0\text{V}$	-	-	0.4	$\mu\text{A}$
Gate-emitter leakage current	$I_{GES}$	$V_{CE}=0\text{V}$ , $V_{GE}=20\text{V}$	-	-	300	nA
Integrated gate resistor	$r_G$		none			$\Omega$

## Electrical Characteristics <sup>2</sup>

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Input capacitance	$C_{ies}$	$V_{CE}=25\text{V}$ , $V_{GE}=0\text{V}$ , $f=1\text{MHz}$ $T_{vj}=25^{\circ}\text{C}$	-	368	-	pF
Output capacitance	$C_{oes}$		-	28	-	
Reverse transfer capacitance	$C_{res}$		-	11	-	

<sup>1</sup> Depending on thermal properties of assembly.

<sup>2</sup> Not subject to production test - verified by design/characterization.

<sup>3</sup> Allowed number of short circuits: <1000; time between short circuits: >1s.